



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Dominik Hartmann et al.
SERIAL NO.: 10/086,405 CONFIRMATION NO.: 1323
FILING DATE: February 28, 2002
TITLE: Apparatus for Placing a Semiconductor Chip as a Flipchip on a Substrate
EXAMINER: Minh N. Trinh
TELEPHONE: (571) 272-4569
FAX: (571) 273-8300
ART UNIT: 3729

CERTIFICATE OF MAILING

I hereby certify that this paper is being deposited with the United States Postal Service as First Class
Mail in an envelope addressed to: Mail Stop ISSUE FEE, Commissioner for Patents, P.O. Box 1450 Alexandria, VA
22313-1450, on the date printed below:

Date: 1/24/06

Name: 

Monica Pizarro

Mail Stop Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria VA 22313-1450

APPLICANT'S COMMENTS ON REASONS FOR ALLOWANCE

These comments are responsive to the Notice of Allowance mailed on October 24, 2005, which sets forth the Examiner's statement of reasons for allowance.

The Examiner is thanked for the kind allowance of all pending claims (i.e. claims 1-20). Applicants acknowledge the Examiner's statement of reasons for allowance as set forth in the Notice of Allowance. However, Applicants point out that the reasons for allowability of the above referenced claims are not limited to the reasons for allowance as set forth in the Notice of Allowance, and that additional reasons for allowability may

exist, each of which may be independently sufficient to establish the patentability of one or more pending claims.

Applicants respectfully reserve the right to introduce, articulate, or otherwise comment on any such additional reasons for allowance as may be appropriate in any future proceedings concerning the claimed invention.

Please charge any additional required fee or credit any overpayment to our deposit account number 50-1698.

Respectfully submitted,
THELEN REID & PRIEST LLP



Dated: January 24, 2006

David B. Ritchie
Reg. No. 31,562

Thelen Reid & Priest LLP
P.O. Box 640640
San Jose, CA 95164-0640
Tel.: 408-292-5800
Fax: 408-287-8040